

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT

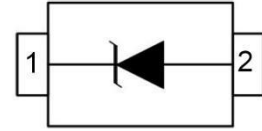


PLED

Product data sheet

Features

- ◆ 250 Watts peak pulse power ($t_p = 8/20\mu s$)
- ◆ Transient protection for high speed data lines to IEC 61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact) IEC 61000-4-4 (EFT) 40A (5/50ns)
- ◆ Protects One Power or I/O Port
- ◆ Low operating and clamping voltages
- ◆ Solid-state silicon avalanche technology



SOD-523

Applications

- ◆ Notebooks, Desktops, Servers and Video Graphics Cards
- ◆ USB Power & Data Line Protection
- ◆ Monitors and Flat Panel Displays
- ◆ I²C Bus Protection
- ◆ Portable Instrumentation
- ◆ Set Top Box

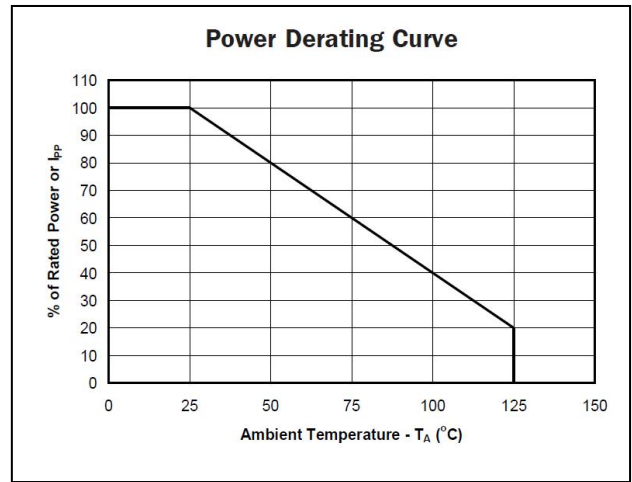
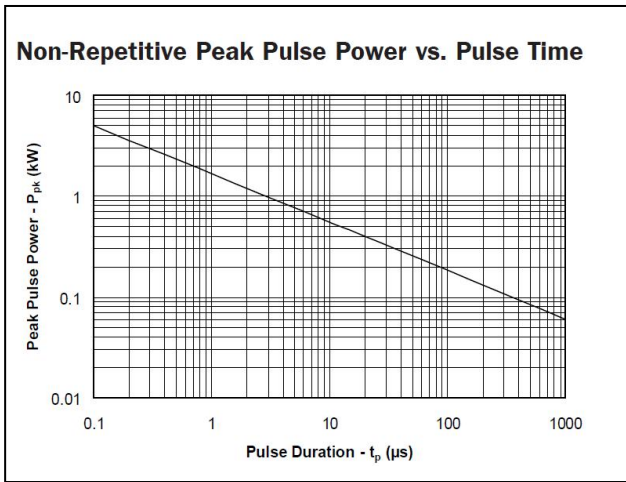
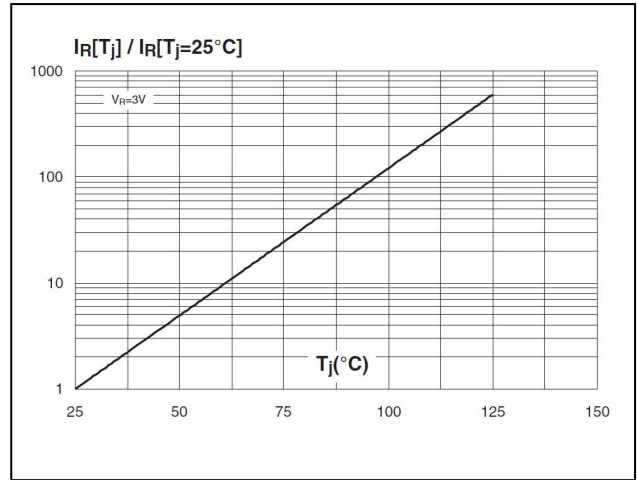
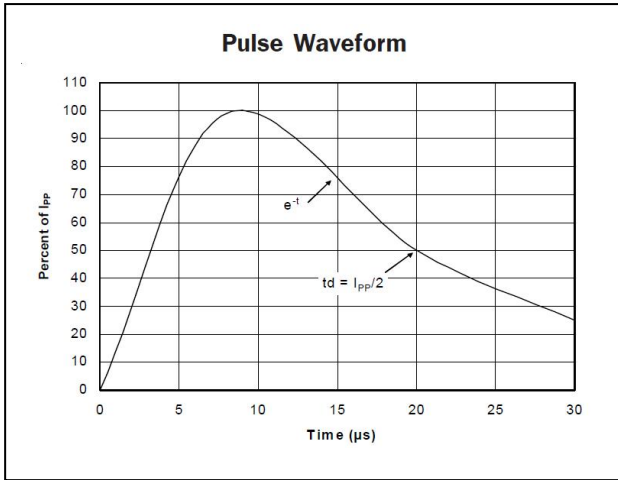
Maximum Rating @ $T_a=25^\circ C$ unless otherwise specified

Symbol	Parameter	Ratings	Units
P_{PK}	Peak Pulse Power ($t_p = 8/20\mu s$)	250	Watts
T_L	Lead Soldering Temperature	260(10sec.)	$^\circ C$
T_J	Operating Temperature	-55 to +125	$^\circ C$
T_{STG}	Storage Temperature	-55 to +150	$^\circ C$

Electrical Characteristics @ $T_a=25^\circ C$ unless otherwise

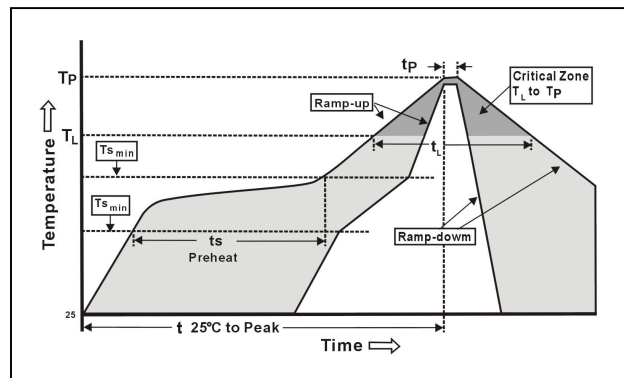
P/N	VRWM @IR		VBR@1mA	VC@1	VC@IPP		CJ
	V	μA	V	V	V	A	pF
		MAX	MIN	MAX	MAX		MAX
PESD3V3S1UB	3.3	1	4	9.8	13	12	120
PESD5V0S1UB	5	1	5.8	11.8	15	10	100
PESD7V0S1UB	7	1	7.5	14	19	8	80
PESD12VS1UB	12	1	13.3	19	25	6	70
PESD15VS1UB	15	1	16.5	24	33	5	50
PESD24VS1UB	24	1	26.1	44	54	3	30
PESD36VS1UB	36	1	38.2	62	80	3	30

Typical Characteristics@ Ta=25°C unless otherwise specified

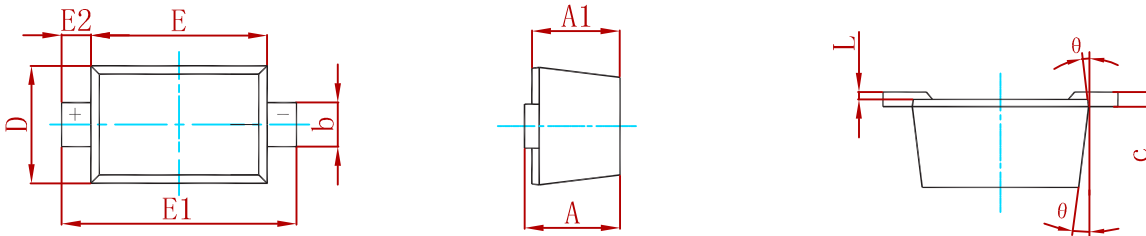


Soldering Parameters

Reflow Condition		Fb – Free assembly
Pre Heat	- Temperature Min ($T_{s(Min)}$)	150°C
	- Temperature Max ($T_{s(Max)}$)	200°C
	- Time (Min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second Max
$T_{s(Max)}$ to T_L - Ramp-up Rate		3°C/second Max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		250 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second Max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C

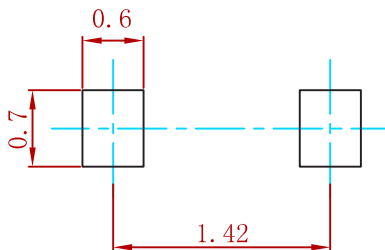


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
θ	7° REF		7° REF	

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
PESDXXXS1UB	SOD-523	3000

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